

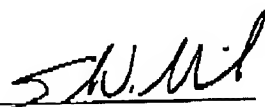
REMARKS

The Examiner has divided the pending claims into two groups, that is, claims 1-12 into Group I and claims 13-20 into Group II, and imposed a restriction requirement between the groups. The Applicants elect to prosecute the invention of Group I, claims 1-12, in this application. Please withdraw claims 13-20 from further consideration in this application, without prejudice to pursuing the withdrawn claims in a divisional or other continuing application. The Applicants plan on filing a divisional application to prosecute the invention of claims 13-20.

The Applicants have also used this opportunity to amend the first paragraph of the specification to include the serial number of a related patent application. Moreover, the Applicants have added claims 21-28 to replace the cancelled claims 13-20. These claims are similar to Group I in that they are apparatus claims directed to wafers having a support body, dies, and tethers. Consideration of these newly added claims is respectfully requested.

In view of the foregoing, the Applicants respectfully request that the restriction requirement be withdrawn upon reconsideration of the application. If the Examiner feels that a telephone conference would be helpful to resolve any remaining issues, the Examiner is respectfully requested to contact the undersigned attorney at (847) 538-7103.

Respectfully submitted,
Shiuh-Hui Steven Chen, et al.

By: 

Thomas V. Miller
Attorney for Applicant
Registration No. 42,002
Phone No.: 847/538-7103
Fax No.: 847/576-3750

APPENDIX A

Version with Markings to Show Changes Made

IN THE SPECIFICATION

The paragraph beginning at line 5 of page 2 has been amended as follows:

This application is related to the following co-pending and commonly assigned patent application, which is hereby incorporated by reference herein: application Ser. No. 10/058,650, entitled "METHOD OF SEPARATING AND HANDLING A THIN SEMICONDUCTOR DIE ON A WAFER," filed on same date herewith, by Shiuh-Hui Steven Chen, Cheryl Field, Didier R. Lefebvre, and Joe Pin Wang, attorney's docket number AP01985.

IN THE CLAIMS

Claims 21-28 have been added as follows:

21. A wafer comprising:
- a support body made of a semiconductor material, the support body having a plurality of apertures and having a first thickness; and
 - a plurality of semiconductor dies each semiconductor die having an integrated circuit formed thereon and having a second thickness, the second thickness being substantially less than the first thickness;
- wherein each of the dies is retained within one of the apertures in the support body such that a gap exists between an outer perimeter of each die and the support body, each die retained within the aperture by a plurality of tethers that extend across the gap and between the outer perimeter of each die and the support body.

22. The wafer of claim 21 wherein at least one of the plurality of tethers is substantially triangular in shape.

23. The wafer of claim 22 wherein the at least one substantially triangular tether has a base and a tip, the base of the tether being attached to the support body of the wafer and the tip of the tether extending across the gap and attached to the die.

24. The wafer of claim 21 wherein at least one of the plurality of tethers has a portion that extends across the gap, the portion extending across the gap having its smallest width adjacent to the outer perimeter of the die.

25. The wafer of claim 21 wherein at least one of the plurality of tethers has a portion that extends across the gap, the portion extending across the gap having at least a portion of a groove.

26. The wafer of claim 21 wherein at least one of the plurality of tethers has a portion that extends across the gap, the portion extending across the gap having at least a portion of a hole.

27. The wafer of claim 21 wherein the integrated circuit formed on the die is adapted for a pressure sensor.

28. The wafer of claim 21 wherein the plurality of tethers are made of a polyimide material.